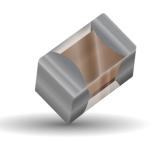
# **RC Equalizer Network**





#### **GENERAL DESCRIPTION**

These ruggedly constructed, ultraminiature (EIA 0402, 1005 metric) equalizers combine high-performance tantalum nitride (TaN) resistive elements and silicon/oxygen/nitrogen (SiON) capacitive elements with KYOCERA AVX's proprietary, automotive-qualified, glass-sandwich FLEXITERM® surface-mount technology, which provides an extra measure of protection against flexure damage during installation. The new GEQ Series equalizers are also manufactured with 100% laser trimming to achieve tight tolerances and offer a low 0.5mm profile, a 125mW power rating, resistance values spanning  $10-50\Omega$ , and capacitance values extending from 1-50pF.

Rated for a wide range of operating temperatures (-55°C to +125°C) and compliant with RoHS, ideal applications for the series extend across the optoelectronic, telecommunications, broadband, military, electronic warfare, space, test, and instrumentation markets and include optical transceiver modules, broadband receivers, and transmission and receiver optical subassemblies (TOSA and ROSA).

#### **FEATURES**

- EIA 0402 Case Size
- Resistance Range: 10 to 50  $\Omega$  typ.
- Capacitance Range: 1 to 50 pF typ.
- **Parallel Configurations**
- Power Rating: 125 mW
- Operating Temperature: -55°C to +125°C
- Laser Trimmed Resistors
- **RoHS Compliant**

### **APPLICATIONS**

- **Optical Transceiver Modules**
- **Broadband Receiver**
- TOSA / ROSA

#### **MARKETS**

- Opto-electronics
- Telecom
- **Broadband Jamming for EW**
- Military
- Instrumentation and Test

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#### **HOW TO ORDER**



3 significant digits R = decimal point



F = 1%



3 significant digits R= decimal point



Capacitance **Tolerance** 

J\* = 5% K\* = 10% M\* =20%

\*Minimum tolerance = +/- 0.1pF





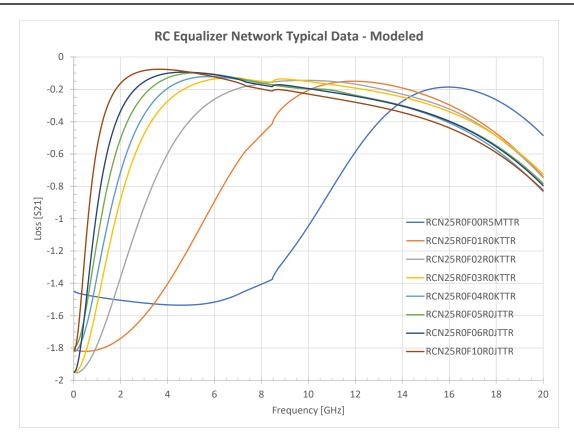
#### **EQUALIZER GAIN SLOPE TABLE**

Part Number	Starting Frequency (Typical) (GHz)	Loss at Starting Frequency (Typical) (dB)	End Frequency (Typical) (GHz)	Loss at End Frequency (Typical) (dB)	Bandwidth (Typical) (GHz)	Gain (Typical) (dB)
RCN09R0F12R5JTTR	0	-0.7	4	-0.05	4	0.65
RCN25R0F00R5MTTR	5	-1.5	16	-0.2	11	1.3
RCN25R0F01R0KTTR	0	-1.8	12	-0.15	12	1.65
RCN25R0F02R0KTTR	0	-1.8	10	-0.15	10	1.65
RCN25R0F03R0KTTR	0	-1.8	7	-0.15	7	1.65
RCN25R0F04R0KTTR	0	-1.8	6	-0.15	6	1.65
RCN25R0F05R0JTTR	0	-1.8	5	-0.15	5	1.65
RCN25R0F06R0JTTR	0	-1.8	4.5	-0.15	4.5	1.65
RCN25R0F10R0JTTR	0	-1.8	3.5	-0.15	3.5	1.65
RCN30R0F0R33MTTR	9.25	-2.9	16	-0.3	6.75	2.6
RCN43R0F1R15KTTR	0	-3	9	-0.15	9	2.85
RCN50R0F0R31MTTR	6	-3.3	16	-0.3	10	3

<sup>\*</sup>For other RC Combinations and EIA Sizes contact factory









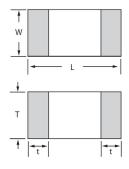
# **RC Equalizer Network**

### **SPECIFICATIONS**

Package Size: EIA 0402 Design: Glass wafer sandwich Termination: NiSn plated Power Rating: 125 mW

Operating Temperature Range: -55°C to +125°C Tolerance: Resistor: 1-5%, Capacitor: 5-20% **Resistance Range:** 10 to 50  $\Omega$  (typical) Capacitance Range: 1 to 50 pF (typical)

### **DIMENSIONS**



Size (EIA)	Length (L)	Width (W)	Thickness (T)	Termination (t)
0402	1.02 ± 0.051	0.51 ± 0.051	0.50 ±0.10	0.25 ± 0.051
	$(0.040 \pm 0.002)$	(0.020 ± 0.002)	(.020 ±.004)	(0.010 ± 0.002)

#### **RESISTOR MATERIAL**

Thin Film Resistors	TaN	
Typical Sheet Resistivity (ohm/sq)	10 to 100	
TCR (ppm/°C, -25 to 125°C)	-100 to -150	
Stability (Change after 1000 hours @ 125°C)	1.0%	

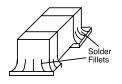
### **CAPACITOR MATERIAL**

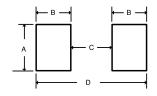
Material	SiON
pF/mm Typical	50 to 100
BDV (v/µm)	600
DF	≤0.1%
TCC (ppm/°C, -25 to 125°C)	±60

#### **ENVIRONMENTAL TESTS**

Reliability Test	Criteria		
Life Test	1000 Hrs. @ 125°C @ 50 mW		
85/85 Temp./ Humidity Breakdown	1080 Hrs. @ 50 mW		
Thermal Cycle	100 cycles @ -40 to 125°C		
Termination Strength	200 g for 50 seconds (Dage Tester)x		

#### SUGGESTED MOUNTING PAD DIMENSIONS



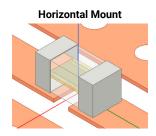


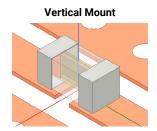
**Normal Pads** 

W = Chip Width L = Chip Length T = Chip Thickness

Case Size	A Min.	B Min.	C Min.	D Min.
0402	0.0213	0.0125	0.0206	0.0436

Dimensions are in inches.





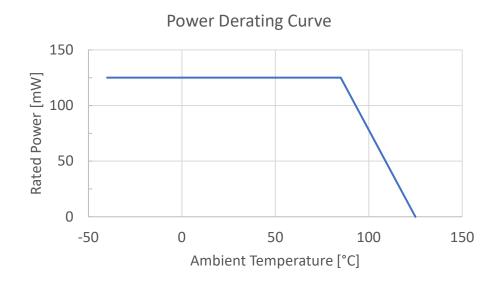
### NOTES:

Mounting will allow the solder fillet to travel up approximately 0.015" of the chip's end and side termination surface. Heavier fillets require a predeposition of solder paste and or an increase in pad dimensions. Typical solder paste application is a .008" to 0.01" thickness with >50% of volume in solder alloy. Can be mounted in both vertical and horizontal orientation without changing electrical performance





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